<ul> <li>Member of the Texas Instruments Widebus<sup>™</sup> Family</li> </ul>	DGG, DGV, OR DL PACKAGE (TOP VIEW)	
<ul> <li>EPIC ™ (Enhanced-Performance Implanted CMOS) Submicron Process</li> </ul>	NC 1 56 GND NC 2 55 NC	
<ul> <li>Latch-Up Performance Exceeds 250 mA Per JESD 17</li> </ul>	Y1 [] 3 54 ]] A1 GND [] 4 53 [] GND	
<ul> <li>ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)</li> </ul>	Y2 [ 5 52 ] A2 Y3 [ 6 51 ] A3	
<ul> <li>Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink</li> </ul>	V <sub>CC</sub> [] 7 50 [] V <sub>CC</sub> Y4 [] 8 49 [] A4 Y5 [] 9 48 [] A5	
Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages	Y6 10 47 A6 GND 11 46 GND	
description	Y7 [ 12 45 ] A7 Y8 [ 13 44 ] A8	
This 18-bit universal bus driver is designed for 1.65-V to 3.6-V V <sub>CC</sub> operation.	Y9 14 43 A9 Y10 15 42 A10 Y11 16 41 A11	
Data flow from A to Y is controlled by the output-enable (OE) input. The device operates in	Y12   17 40   A12 GND   18 39   GND	
the transparent mode when the latch-enable ( $\overline{LE}$ ) input is low. The A data is latched if the clock (CLK) input is held at a high or low logic level. If $\overline{LE}$ is	Y13 [ 19 38 ] A13 Y14 [ 20 37 ] A14	
high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When OE is	Y15 [ 21 36 ] A15 V <sub>CC</sub> [ 22 35 ] V <sub>CC</sub> Y16 [ 23 34 ] A16	
high, the outputs are in the high-impedance state.	Y17 24 33 A17 GND 25 32 GND	

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ALVC16834 is characterized for operation from -40°C to 85°C.

Y5 [	9	48	LI A5
Y6 [	10	47	<b>A</b> 6
GND [	11	46	GND
Y7 [	12	45	] A7
Y8 [	13	44	] A8
Y9 [	14	43	] A9
Y10	15	42	A10
Y11 [	16	41	] A11
Y12 [	17	40	A12
GND [	18	39	] GND
Y13 [	19	38	A13
Y14 [	20	37	]A14
Y15 [	21	36	] A15
V <sub>CC</sub> [	22	35	Vcc
Y16 [	23	34	]A16
Y17 [	24	33	]A17
GND [	25	32	] GND
Y18 [	26	31	]A18
OE [	27	30	]CLK
LE [	28	29	] GND

NC - No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 1999, Texas Instruments Incorporated

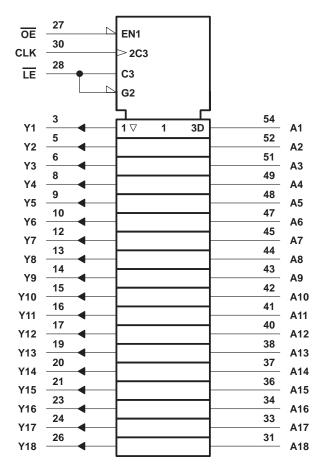
#### FUNCTION TABLE

	INPUTS						
OE	LE	CLK	Α	Y			
Н	Х	Х	Х	Z			
L	L	Х	L	L			
L	L	Х	Н	Н			
L	Н	$\uparrow$	L	L			
L	Н	$\uparrow$	Н	Н			
L	Н	Н	Х	Y0‡ Y0‡			
L	Н	L	Х	Y0‡			

<sup>†</sup> Output level before the indicated steady-state input conditions were established, provided that CLK is high before  $\overline{\text{LE}}$  goes high

<sup>‡</sup> Output level before the indicated steady-state input conditions were established

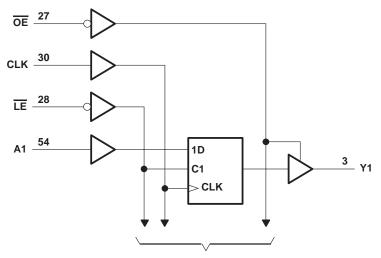
# logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To 17 Other Channels

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Input voltage range, V <sub>I</sub> (see Note 1) Output voltage range, V <sub>O</sub> (see Notes 1 and 2) Input clamp current, $I_{IK}$ (V <sub>I</sub> < 0) Output clamp current, $I_{OK}$ (V <sub>O</sub> < 0) Continuous output current, $I_O$ Continuous current through each V <sub>CC</sub> or GND	-0.5 V to 4.6 V -0.5 V to 4.6 V -0.5 V to 4.6 V -0.5 V to V <sub>CC</sub> + 0.5 V -50 mA ±50 mA ±100 mA : DGG package 81°C/W DGV package 86°C/W
Storage temperature range. Teta	DL package
5 i 3 3 3 3 1 3 1 3 1 3 1 3 1 3 1 3 1 3 1	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.



# recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		1.65	3.6	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
VIH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		V <sub>CC</sub> = 2.7 V to 3.6 V	2		
	L Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
VIL Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	
VI	Input voltage		0	VCC	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-4	
1		$V_{CC} = 2.3 V$		-12	
ЮН	High-level output current	$V_{CC} = 2.7 V$		-12	mA
	/I Input voltage	$V_{CC} = 3 V$		-24	
		V <sub>CC</sub> = 1.65 V		4	
la:	Low lovel output ourrent	V <sub>CC</sub> = 2.3 V		12	mA
UCL		V <sub>CC</sub> = 2.7 V		12	mA
	V <sub>CC</sub> = 3 V			24	
$\Delta t / \Delta v$	Input transition rise or fall rate			10	ns/V
ТА	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



P	ARAMETER	TEST CONDITIONS	Vcc	MIN	түр†	MAX	UNIT	
		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> -0.2				
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2				
		$I_{OH} = -6 \text{ mA}$	2.3 V	2				
V <sub>OH</sub>		2.3 V	1.7			V		
·0n		I <sub>OH</sub> = -12 mA	2.7 V	2.2				
			3 V	2.4				
		I <sub>OH</sub> = -24 mA	3 V	2				
		l <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2		
		I <sub>OL</sub> = 4 mA	1.65 V			0.45		
		I <sub>OL</sub> = 6 mA	2.3 V			0.4	V	
VOL		40	2.3 V			0.7	V	
		$I_{OL} = 12 \text{ mA}$	2.7 V			0.4		
		I <sub>OL</sub> = 24 mA	3 V			0.55		
Ιį		V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V			±5	μΑ	
IOZ		V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V			±10	μΑ	
ICC		$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	3.6 V			40	μΑ	
∆ICC		One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND	3 V to 3.6 V			750	μΑ	
	Control inputs		2.2.1		4			
Ci	Data inputs	$V_{I} = V_{CC} \text{ or } GND$	3.3 V		5.5		pF	
Co	Outputs	$V_{O} = V_{CC}$ or GND	3.3 V		7		pF	

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

 $^{\dagger}$  All typical values are at V\_CC = 3.3 V, T\_A = 25°C.

# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

		V <sub>CC</sub> =	1.8 V	V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub> Clock frequency			‡		150		150		150	MHz		
t <sub>w</sub> Pulse duration	LE low		‡		3.3		3.3		3.3		50	
	Puise duration	CLK high or low		‡		3.3		3.3		3.3		ns
	Data before CLK↑			‡		2.1		2.1		1.7		
t <sub>su</sub>	Setup time		CLK high	‡		2.2		2.3		1.9		ns
		Data before LE↑ CLK low	‡		1.5		1.9		1.5			
		Data after CLK↑		‡		0.6		0.6		0.7		
t <sub>h</sub>	Hold time	Data after LE↑	CLK high or low	‡		0.8		0.8		0.9		ns

<sup>‡</sup> This information was not available at the time of publication.



# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		(001-01)	MIN	MIN TYP	MIN	MAX	MIN	MAX	MIN	MAX	
fmax			†		150		150		150		MHz
	A			†	1	4.4		4.2	1	3.6	
<sup>t</sup> pd	LE	Y		†	1.3	6		5.9	1.5	4.9	ns
	CLK			†	1.2	6		5.3	1.5	4.6	
ten	OE	Y		†	1.4	5.6		5.6	1.5	5	ns
<sup>t</sup> dis	OE	Y		†	1	4		4.7	1.8	4.5	ns

<sup>†</sup> This information was not available at the time of publication.

# switching characteristics from 0°C to 65°C, $C_L$ = 50 pF

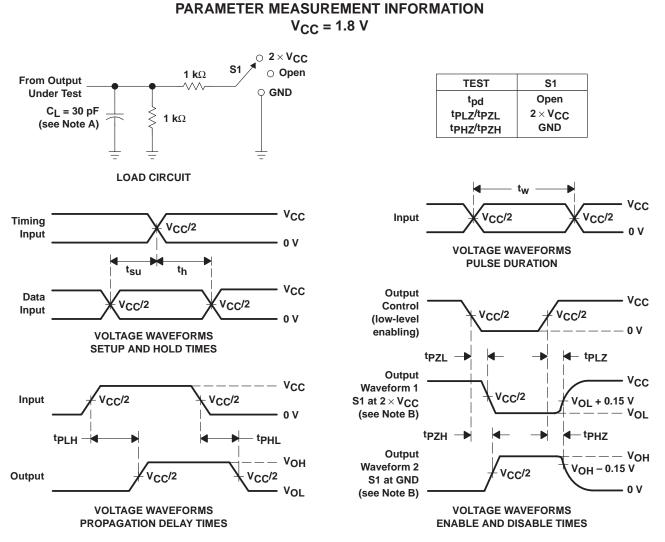
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1	UNIT	
	(INFOT)	(6611 61)	MIN	MAX	
tpd	CLK	Y	1.7	4.3	ns

# operating characteristics, $T_A = 25^{\circ}C$

PARAMETER T		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V V <sub>CC</sub> = 2.5 V V <sub>CC</sub> = 3.3		UNIT		
		TEST CONDITIONS	TYP	TYP	ТҮР	UNIT		
Г			Outputs enabled	C 0 _ f _ 10 MH=	†	38	41	рF
L	C <sub>pd</sub>	Power dissipation capacitance	Outputs disabled	$C_{L} = 0$ , $f = 10 \text{ MHz}$ †	13	15	рг	

<sup>†</sup> This information was not available at the time of publication.



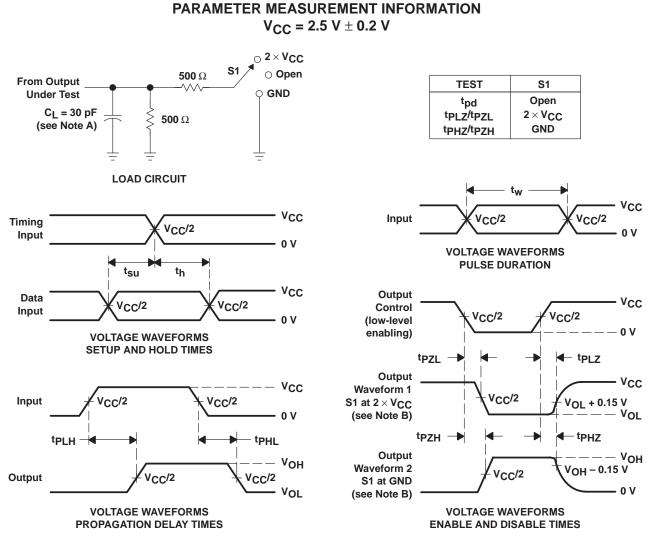


### NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

# Figure 1. Load Circuit and Voltage Waveforms



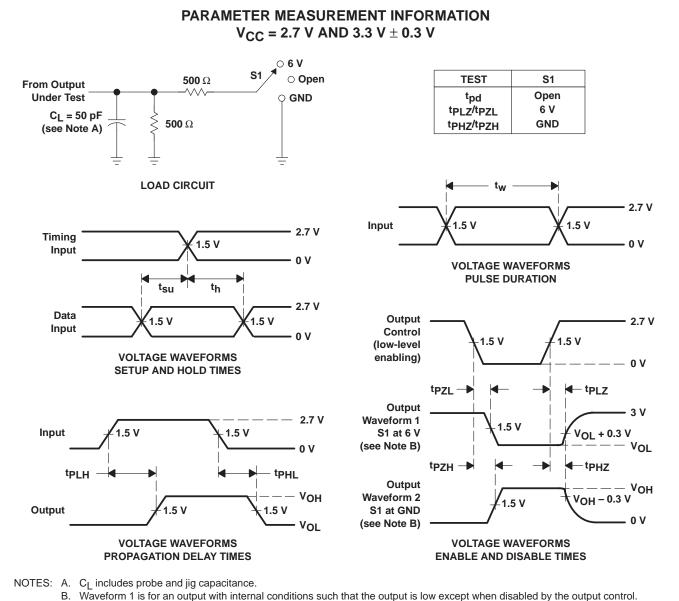


NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>Q</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
- C. D. The outputs are measured one at a time with one transition per measurement.
- E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. tPLH and tPHL are the same as tpd.

# Figure 2. Load Circuit and Voltage Waveforms





- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. tPLH and tPHL are the same as tpd.

### Figure 3. Load Circuit and Voltage Waveforms



### **IMPORTANT NOTICE**

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1999, Texas Instruments Incorporated